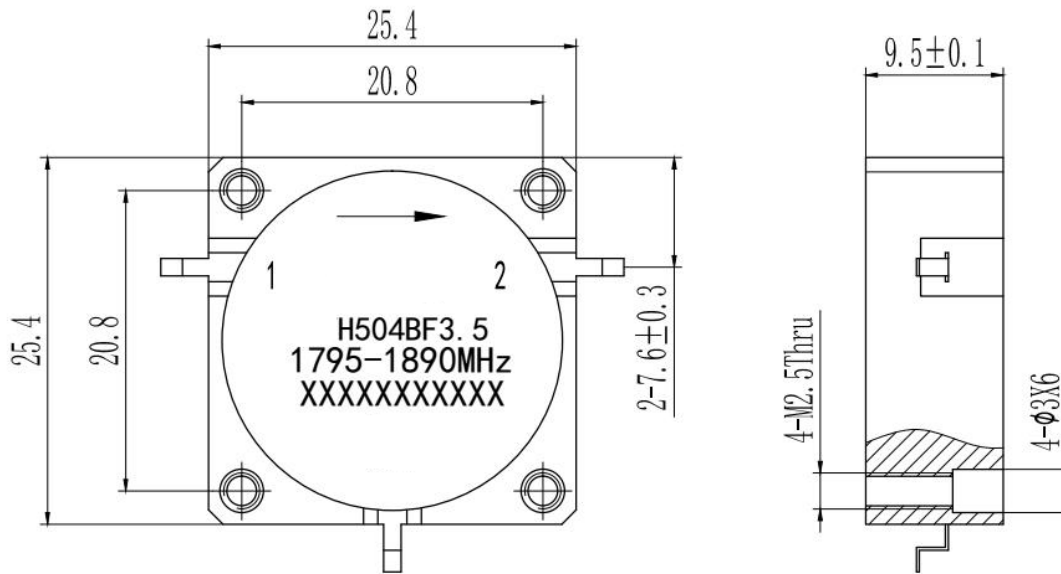


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H504B3.5[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-70
H504B3.0[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-72
H504B3.0[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.5[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.0[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.5[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.0[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75
H504B3.5[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75